



Product Change Notification: CBOL-23HZDP733

Date:

28-Jul-2026

Product Category:

Ethernet Switches

Notification Subject:

CCB 6910.005 Final Notice: Qualification of MTAI as an additional assembly site for KSZ8563RNXV-VAO, KSZ8563RNXI, KSZ9563RNXC, KSZ9893RNXI-TR, KSZ8563RNXV-TRVAO, KSZ8563RNXV-TR, KSZ8563RNXV, KSZ9563RNXI-TR, KSZ8563RNXI-TR, KSZ9563RNXI, KSZ9563RNXC-TR, KSZ9893RNXC-TR, KSZ9893RNXC and KSZ9893RNXI catalog part numbers (CPN) available in 64L VQFN (8x8x0.9mm) package.

Affected CPNs:

[CBOL-23HZDP733_Affected_CPN_07282026.pdf](#)

[CBOL-23HZDP733_Affected_CPN_07282026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MTAI as an additional assembly site for KSZ8563RNXV-VAO, KSZ8563RNXI, KSZ9563RNXC, KSZ9893RNXI-TR, KSZ8563RNXV-TRVAO, KSZ8563RNXV-TR, KSZ8563RNXV, KSZ9563RNXI-TR, KSZ8563RNXI-TR, KSZ9563RNXI, KSZ9563RNXC-TR, KSZ9893RNXC-TR, KSZ9893RNXC and KSZ9893RNXI catalog part numbers (CPN) available in 64L VQFN (8x8x0.9mm) package.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Note: This is a qualification by similarity (QBS) to CCB# 3472, CCB# 6910 and CCB# 7167

Revision History: July 28, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_CBOL-23HZDP733_Qual Report CCB6910.pdf](#)

[PCN_CBOL-23HZDP733_Qual Report CCB7167.pdf](#)

[PCN_CBOL-23HZDP733 Qual Report CCB3472.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN):

KSZ8563RNXV-VAO

KSZ8563RNXI

KSZ9563RNXC

KSZ9893RNXI-TR

KSZ8563RNXV-TRVAO

KSZ8563RNXV-TR

KSZ8563RNXV

KSZ9563RNXI-TR

KSZ8563RNXI-TR

KSZ9563RNXI

KSZ9563RNXC-TR

KSZ9893RNXC-TR

KSZ9893RNXC

KSZ9893RNXI



QUALIFICATION REPORT SUMMARY

RELIABILITY LABORATORY

PCN #: CBOL-23HZDP733

Date:
Dec 12, 2018

Qualification of MTAI as an additional assembly site for KSZ8563RNXV-VAO, KSZ8563RNXI, KSZ9563RNXC, KSZ9893RNXI-TR, KSZ8563RNXV-TRVAO, KSZ8563RNXV-TR, KSZ8563RNXV, KSZ9563RNXI-TR, KSZ8563RNXI-TR, KSZ9563RNXI, KSZ9563RNXC-TR, KSZ9893RNXC-TR, KSZ9893RNXC and KSZ9893RNXI catalog part numbers (CPN) available in 64L VQFN (8x8x0.9mm) package. This is a Q006 qualification.



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PACKAGE QUALIFICATION REPORT

Purpose	Qualification of MTAI as an additional assembly site for KSZ8563RNXV-VAO, KSZ8563RNXI, KSZ9563RNXC, KSZ9893RNXI-TR, KSZ8563RNXV-TRVAO, KSZ8563RNXV-TR, KSZ8563RNXV, KSZ9563RNXI-TR, KSZ8563RNXI-TR, KSZ9563RNXI, KSZ9563RNXC-TR, KSZ9893RNXC-TR, KSZ9893RNXC and KSZ9893RNXI catalog part numbers (CPN) available in 64L VQFN (8x8x0.9mm) package. This is a Q006 qualification.
CN	ES315137
QUAL ID	Q19140 Rev. A
MP CODE	TA7A19G4XV01
Part No.	UCS2112-1-V/G4-V01
Bonding No.	BDM-001754 REV. E
CCB No.	3472
<u>Package</u>	
Type	20L QFN
Package size	4x4x0.9 mm
<u>Lead Frame</u>	
Paddle size	114 x 114 mils
Material	A194
Surface	Bare Copper
Process	Etched
Lead Lock	No
Part Number	10102017
<u>Material</u>	
Epoxy	8006NS
Wire	CuPdAu wire
Mold Compound	G700LTD
Plating Composition	Matte Tin



MICROCHIP PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MTAI201802701.000	TC05920169778.100	1931UYJ
MTAI201802725.000	TC05920169778.100	193110V
MTAI201802726.000	TC05920169778.100	193110W

Result

☒ Pass ☐ Fail ☐ _____

20L QFN (4x4x0.9 mm) assembled by MTAI pass reliability test per QCI-39000.
This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C
reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
Moisture/Reflow Sensitivity Classification Test (At MSL Level 1)	85°C/ 85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 (IPC/JEDEC J-STD-020E)	IPC/JEDEC C J-STD- 020E	135	0/135	Pass	

<u>Precondition</u> <u>Prior Perform</u> <u>Reliability Tests</u> (At MSL Level 1)	Electrical Test :+25°C and 125°C System: J750 Bake 150°C, 24 hrs System: CHINEE 85°C/85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 Electrical Test :+25°C and 125°C System: J750	JESD22- A113	693(0)	693 693 693 693 0/693	 Pass	Good Devices
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PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	Stress Condition: -65°C to +150°C, 500 Cycles System : TABAI ESPEC TSA-70H Electrical Test: + 105°C System: J750	JESD22-A104		231		Parts had been pre-conditioned at 260°C
			231(0)	0/231	Pass	
	Bond Strength: Wire Pull (>4.00 grams) Bond Shear (>18.00 grams)		45 (0)	0/45	Pass	
	Stress Condition: -65°C to +150°C, 1000 Cycles System : TABAI ESPEC TSA-70H Electrical Test: + 105°C System: J750		231(0)	0/231	Pass	
	Bond Strength: Wire Pull (>4.00 grams) Bond Shear (>18.00 grams)		45 (0)	0/45	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
HAST	Stress Condition: +130°C/85%RH, 96 hrs. Bias Volt: 5.5 Volts System: HAST 6000X	JESD22-A110		231		Parts had been pre-conditioned at 260°C
	Electrical Test: + 25°C and 105°C System: J750		231(0)	0/231	Pass	77 units / lot
	Bond Strength: Wire Pull (>4.00 grams) Bond Shear (>18.00 grams)		45 (0)	0/45	Pass	
	Stress Condition: +130°C/85%RH, 192 hrs. Bias Volt: 5.5 Volts System: HAST 6000X			231		
	Electrical Test: + 25°C and 105°C System: J750		231(0)	0/231	Pass	
	Bond Strength: Wire Pull (>4.00 grams) Bond Shear (>18.00 grams)		45 (0)	0/45	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
UNBIASED-HAST	Stress Condition: +130°C/85%RH, 96 hrs. System: HAST 6000X	JESD22-A118		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: J750		231(0)	0/231	Pass	77 units / lot
	Stress Condition: +130°C/85%RH, 192 hrs. System: HAST 6000X			231		
	Electrical Test: +25°C System: J750		231(0)	0/231	Pass	
High Temperature Storage Life	Stress Condition: Bake 175°C, 500 hrs System: SHEL LAB	JESD22-A103		135		45 units / lot
	Electrical Test :+25°C and 105°C System: J750		135(0)	0/135	Pass	
	Stress Condition: Bake 175°C, 1000 hrs System: SHEL LAB			135		
	Electrical Test :+25°C and 105°C System: J750		135(0)	0/135	Pass	
Solderability Temp 215°C	Steam Aging: Temp 93°C,8Hrs System: SAS-3000 Solder Dipping: Solder Temp.215°C Solder material: SnPb Sn63,Pb37 System: ERSA RA 2200D Visual Inspection: External Visual Inspection	J-STD-002	22 (0)	22 22 0/22	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Bond Strength Data Assembly	Wire Pull (> 4.00 grams)	M2011	30 (0) Wires	0/30	Pass	
	Bond Shear (>18.00 grams)	JESD22- B116	30 (0) bonds	0/30	Pass	



QUALIFICATION REPORT

RELIABILITY LABORATORY

PCN #: CBOL-23HZDP733

Date:

March 4, 2025

Qualification of MTAI as an additional assembly site for KSZ8563RNXV-VAO, KSZ8563RNXI, KSZ9563RNXC, KSZ9893RNXI-TR, KSZ8563RNXV-TRVAO, KSZ8563RNXV-TR, KSZ8563RNXV, KSZ9563RNXI-TR, KSZ8563RNXI-TR, KSZ9563RNXI, KSZ9563RNXC-TR, KSZ9893RNXC-TR, KSZ9893RNXC and KSZ9893RNXI catalog part numbers (CPN) available in 64L VQFN (8x8x0.9mm) package. This is a Q006 grade 3 qualification.



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PACKAGE QUALIFICATION REPORT

Purpose	Qualification of MTAI as an additional assembly site for KSZ8563RNXV-VAO, KSZ8563RNXI, KSZ9563RNXC, KSZ9893RNXI-TR, KSZ8563RNXV-TRVAO, KSZ8563RNXV-TR, KSZ8563RNXV, KSZ9563RNXI-TR, KSZ8563RNXI-TR, KSZ9563RNXI, KSZ9563RNXC-TR, KSZ9893RNXC-TR, KSZ9893RNXC and KSZ9893RNXI catalog part numbers (CPN) available in 64L VQFN (8x8x0.9mm) package. This is a Q006 grade 3 qualification.
CN	E000246496
QUAL ID	R2401317 Rev. A
MP CODE	STB071KDXC50
Part No.	USX5007C/KD
Bonding No.	BD-002245 Rev. 01
CCB No.	6910
<u>Package</u>	
Type	100L VQFN
Package size	12 x 12 x 0.9mm
<u>Lead Frame</u>	
Paddle size	323x323mils
Material	EFTEC64
Surface	Ag signal ring plated on DAP
Process	Etched
Lead Lock	No
Part Number	10110011
Treatment	Roughening
<u>Material</u>	
Epoxy	QMI519
Wire	CuPdAu
Mold Compound	G700LTD
Plating Composition	Matte Sn



MICROCHIP **PACKAGE QUALIFICATION REPORT**

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MTAI252600940.000	TC14924313854.200	2439YD7
MTAI252601144.000	TC14924313854.200	2439YT8
MTAI252601148.000	TC14924313854.200	2439YTK

Result

☒ Pass ☐ Fail ☐ _____

100L VQFN (12x12x0.9mm) assembled by MTAI pass reliability test per QCI-39000.
This package was qualified the Moisture/Reflow Sensitivity Classification Level 3 at 260°C
reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
Moisture/Reflow Sensitivity Classification Test (At MSL Level 3)	30°C/ 60%RH Moisture Soak 192 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 (IPC/JEDEC J-STD-020E)	IPC/JEDEC C J-STD- 020E	135(0)	0/135	Pass	
Precondition Prior Perform Reliability Tests (At MSL Level 3)	Electrical Test: +25°C and 85°C System: LTX_D1X Bake 150°C, 24 hrs System: CHINEE 30°C/60%RH Moisture Soak 192 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 Electrical Test: +25°C and 85°C System: LTX_D1X	JESD22- A113	693(0)	0/693 693 693 693 0/693	Pass Pass	Good Devices

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	Stress Condition: -55°C to +125°C, 500 Cycles System : VOTSCH Electrical Test: +25°C and 85°C System: LTX_D1X Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>8.00 grams)	JESD22-A104		231		Parts had been pre-conditioned at 260°C
			231(0)	0/231	Pass	
			45 (0)	0/45	Pass	
	Stress Condition: -55°C to +125°C, 1000 Cycles System: VOTSCH Electrical Test: +25°C and 85°C System: LTX_D1X Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>8.00 grams)			231		
			231(0)	0/231	Pass	
			45 (0)	0/45	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
HAST	Stress Condition: +110°C/85%RH, 264 hrs. Bias Volt: PS1:1.32 Volts, PS3: 3.63 Volts System: HAST 6000X Electrical Test: +25°C and 85°C System: LTX_D1X Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>8.00 grams)	JESD22-A110		231		Parts had been pre-conditioned at 260°C
			231(0)	0/231	Pass	77 units / lot
			45 (0)	0/45	Pass	
				231		
			231(0)	0/231	Pass	
			45 (0)	0/45	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
UNBIASED-HAST	Stress Condition: +110°C/85%RH, 264 hrs. System: HAST 6000X	JESD22-A118		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: LTX_D1X		231(0)	0/231	Pass	77 units / lot
High Temperature Storage Life	Stress Condition: Bake 150°C, 500 hrs System: CHINEE	JESD22-A103		135		45 units / lot
	Electrical Test: +25°C and 85°C System: LTX_D1X		135(0)	0/135	Pass	
	Stress Condition: Bake 150°C, 1000 hrs System: CHINEE			135		
	Electrical Test: +25°C and 85°C System: LTX_D1X		135(0)	0/135	Pass	
Bond Strength Data Assembly	Wire Pull (> 3.00 grams)	Mil. Std. 883-2011	30 (0) Wires	0/30	Pass	
	Bond Shear (>8.00 grams)	CDF-AEC-Q100-001	30 (0) Bonds	0/30	Pass	



QUALIFICATION REPORT

RELIABILITY LABORATORY

PCN #: CBOL-23HZDP733

Date:
Dec 12, 2018

Qualification of MTAI as an additional assembly site for KSZ8563RNXV-VAO, KSZ8563RNXI, KSZ9563RNXC, KSZ9893RNXI-TR, KSZ8563RNXV-TRVAO, KSZ8563RNXV-TR, KSZ8563RNXV, KSZ9563RNXI-TR, KSZ8563RNXI-TR, KSZ9563RNXI, KSZ9563RNXC-TR, KSZ9893RNXC-TR, KSZ9893RNXC and KSZ9893RNXI catalog part numbers (CPN) available in 64L VQFN (8x8x0.9mm) package. This is a Q006 grade 2 qualification.



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PACKAGE QUALIFICATION REPORT

Purpose	Qualification of MTAI as an additional assembly site for KSZ8563RNXV-VAO, KSZ8563RNXI, KSZ9563RNXC, KSZ9893RNXI-TR, KSZ8563RNXV-TRVAO, KSZ8563RNXV-TR, KSZ8563RNXV, KSZ9563RNXI-TR, KSZ8563RNXI-TR, KSZ9563RNXI, KSZ9563RNXC-TR, KSZ9893RNXC-TR, KSZ9893RNXC and KSZ9893RNXI catalog part numbers (CPN) available in 64L VQFN (8x8x0.9mm) package. This is a Q006 grade 2 qualification.
CN	E000246922
QUAL ID	R2401318 Rev. A
MP CODE	STGB19PUAVA1
Part No.	KSZ9031RNXVB-VAO
Bonding No.	A-069549 Rev.B
CCB No.	7167
<u>Package</u>	
Type	48L VQFN-WFS
Package size	7 x 7 mm
<u>Lead Frame</u>	
Paddle size	224 x 224mils
Material	A194
Surface	Ag ring plated on DAP
Process	Etched
Lead Lock	No
Part Number	10104818
Treatment	Roughening
<u>Material</u>	
Epoxy	3280
Wire	CuPdAu
Mold Compound	G700LTD
Plating Composition	Matte Sn



MICROCHIP PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MTAI252701468.000	TC14924145440.800	24406MT
MTAI252701543.000	TC14924145440.800	244071K
MTAI252701558.000	TC14924145440.800	244073A

Result

☒ Pass ☐ Fail ☐ _____

48L VQFN-WFS (7x7 mm) assembled by MTAI pass reliability test per QCI-39000.
This package was qualified the Moisture/Reflow Sensitivity Classification Level 3 at 260°C
reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
Moisture/Reflow Sensitivity Classification Test (At MSL Level 3)	30°C/ 60%RH Moisture Soak 192 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 (IPC/JEDEC J-STD-020E)	IPC/JEDEC C J-STD- 020E	0135	0/135	Pass	
Precondition Prior Perform Reliability Tests (At MSL Level 3)	Electrical Test: +25°C, 85°C and 110°C System: LTX_D1X_HI_CFG Bake 150°C, 24 hrs System: CHINEE 30°C/60%RH Moisture Soak 192 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 Electrical Test: +25°C, 85°C and 110°C System: LTX_D1X_HI_CFG	JESD22- A113	693(0) 693(0)	0/693 693 693 693 0/693	Pass Pass	Good Devices

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	Stress Condition: -55°C to +125°C, 1000 Cycles System : TABAI ESPEC TSA-70H Electrical Test: +25°C, 85°C and 110°C System: LTX_D1X_HI_CFG	JESD22-A104		231		Parts had been pre-conditioned at 260°C
			231(0)	0/231	Pass	
	Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>10.00 grams)		45(0)	0/45	Pass	
	Stress Condition: -55°C to +125°C, 2000 Cycles System: TABAI ESPEC TSA-70H Electrical Test: +25°C, 85°C and 110°C System: LTX_D1X_HI_CFG Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>10.00 grams)			231		
			231(0)	0/231	Pass	
			45(0)	0/45	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
HAST	Stress Condition: +110°C/85%RH, 264 hrs. Bias Volt: VDD1=3.3Volts, VDD2=1.2Volts System: HAST 6000X	JESD22-A110		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C,85°C and 110°C System: LTX_D1X_HI_CFG		231(0)	0/231	Pass	77 units / lot
	Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>10.00 grams)		45(0)	0/45	Pass	
	Stress Condition: +110°C/85%RH, 528 hrs. Bias Volt: VDD1=3.3Volts,VDD2=1.2Volts System: HAST 6000X			231		
	Electrical Test: +25°C,85°C and 110°C System: LTX_D1X_HI_CFG		231(0)	0/231	Pass	
	Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>10.00 grams)		45(0)	0/45	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
UNBIASED-HAST	Stress Condition: +110°C/85%RH, 264 hrs. System: HAST 6000X	JESD22- A118		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C,85°C and 110°C System: LTX_D1X_HI_CFG		231(0)	0/231	Pass	77 units / lot
High Temperature Storage Life	Stress Condition: Bake 150°C, 500 hrs System: CHINEE	JESD22- A103		135		45 units / lot
	Electrical Test: +25°C,85°C and 110°C System: LTX_D1X_HI_CFG		135(0)	0/135	Pass	
	Stress Condition: Bake 150°C, 1000 hrs System: CHINEE			135		
	Electrical Test: +25°C,85°C and 110°C System: LTX_D1X_HI_CFG		135(0)	0/135	Pass	
Solderability Temp 245°C	Steam Aging: Temp 93°C,8Hrs System: SAS-3000 Solder Dipping: Solder Temp.245°C Solder material: Pb Free Sn 95.5Ag3.9 Cu0.6 System: ERSA RA 2200D Visual Inspection: External Visual Inspection	J-STD- 002		0/22		
			22(0)	0/22	Pass	

Physical Dimensions	Physical Dimension, 10 units from 1 lot	JESD22- B100/B108	30(0) Units	0/30	Pass	
Bond Strength Data Assembly	Wire Pull (> 3.00 grams)	Mil. Std. 883-2011	30 (0) Wires	0/30	Pass	
	Bond Shear (>10.00 grams)	CDF-AEC- Q100-001	30 (0) Bonds	0/30	Pass	